

Photoresist Product Road Map: Overview

Next Generation Lithography

FEP-100 Positive resists for EBDW

FEN-100 Negative resists for EBDW

EUV

ArF (193nm) DUV Lithography

GAR-8000 Series High Resolution ArF

GAR-9000 For Immersion Lithography

GAR-7000 Series ArF Single layer

TIS-2000 ArF Bilayer (Si-contg. resist)

KrF (248nm) DUV Lithography

GKR-4000 for thick film ion implant

ARCH-8000 for CH for Dense & Iso lines

GKR-5000 Series High Resolution Resists for CH with HT PSM

GKR-6000 Series High Resolution Resists for Dense & Iso lines

TIS-2000 for KrF Backend (Si-contg. resist)

Baseline resists for Multiple use

OiR 600 Series for high resolution i-line

OiR 800 Series

OiR 900 Series

i-Line (365nm) Lithography



Lithography Node (nm)

Product Descriptions

248 nm Single Layer

GKR 6102	Sub 150nm Multi-Purpose
GKR 5317V3	Advanced Contact Hole Resist
GKR 4400	Thick Film Resist
GKR 5303	200 nm Contact Hole
ARCH 8250	250 nm Multi-Purpose Resist

193 nm Single Layer

GAR-8105G1	90nm Dense Lines
GAR-7307Y2	120nm Contact Holes
GAR-8205B15	Multi-Purpose

TIS 2000 Bi-Layer

TIS 248IL-01-23	248nm Imaging Layer
TIS 248UL-01-50	248nm Under Layer
TIS 193IL-54-20	193nm Imaging Layer
TIS 193UL-52-50	193nm Under Layer

For additional product line technical information:

248nm product line technical contact:

➤ **David_Brzozowy@fujifilm-ffem.com**

193nm product line technical contact:

➤ **Thomas_Sarubbi@fujifilm-ffem.com**